

3-D Engineering Corp.

Professional Engineering Services:
Technology Development, Research & Development,
CAD Design , Manufacturing, Assembly,
Test & Integration

Woman Owned Small Business (WOSB)

Linda S. Luoma

President

3-D Engineering Corporation

Susan E. Boone

Vice President Business Development

3-D Engineering Corporation

Roy S. Luoma

Vice President Engineering

3-D Engineering Corporation

Robert Shein

Vice President Manufacturing

3-D Engineering Corporation

3-D Engineering Corp Proprietary Information,
Do Not Duplicate Or Distribute

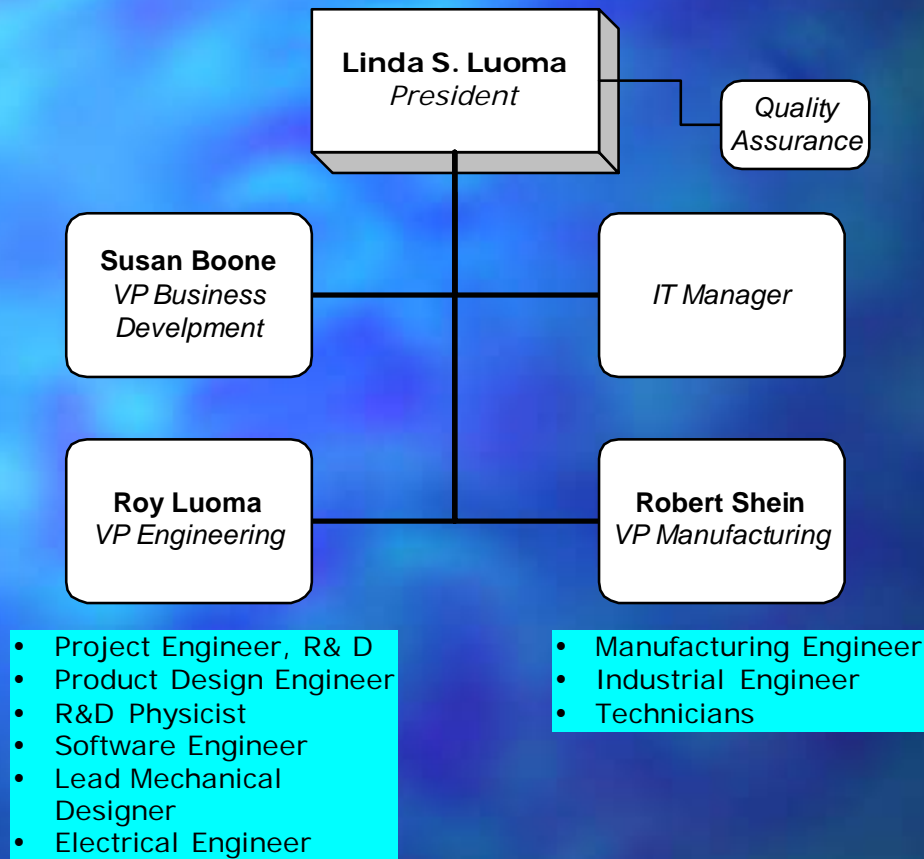


Company Introduction



- 3-D Engineering Corp. was formed in July 1998
- Provides world class research & design development services ranging from requirements definition through system deployment
- Process driven organization with highly automated data management systems
- Provides services on-site or from our location in Temecula, California
- Collaborate with our customers to provide a near seamless research & design development capability and systems engineering approach

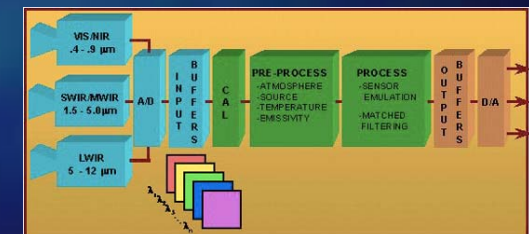
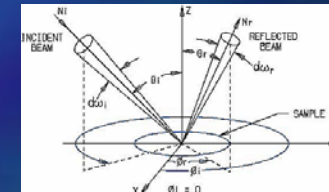
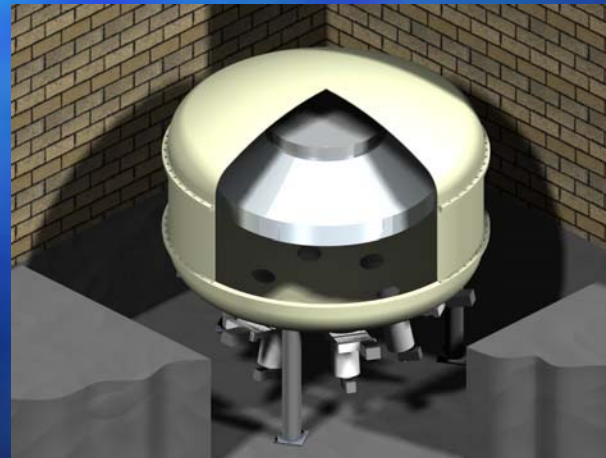
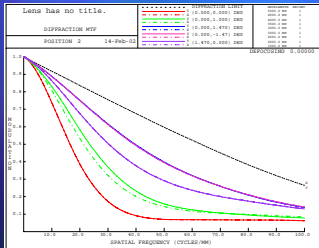
3-D Organization



3-D Engineering maintains agreements with associates to supplement our core capabilities

Capabilities Overview

- Research And Development
- Mechanical, Electrical, & Software Engineering Design
- Engineering Analysis
- Configuration Management
- Test, Evaluation & Integration
- Manufacturing (Including Prototype & Small Run Production)



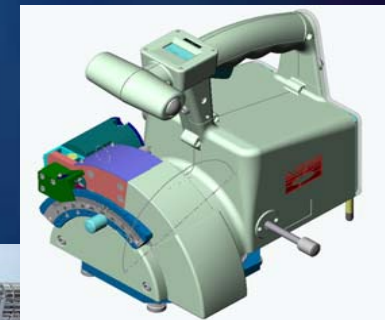
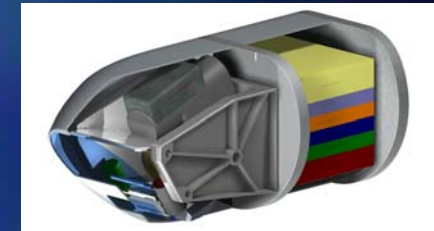
Research and Development

- Provide Efficient and Highly Consistent Research & Development Employing Proven Processes, Technologies, and Experienced Engineers.
 - Conducted Technology Assessments and Feasibility Studies For Resolving “Best Method” Or “Best Approach” for Developing New Technology .
 - Development Of Working Hardware (Brass boards) To Demonstrate Performance Of Selected Technical Approach.
 - Perform Test and Evaluation for design principles and critical operating parameters.
 - Generation of Specification Control Documents (SCD) for System and Module Level Requirements.
 - Development Of Prototype “Technology Demonstrators” for field tests.
 - Development Of Systems for Pilot Production.
 - Design Refinement and Documentation Tasking for FSD (i.e., Production Drawings, Test Reports, CDRL’s, SCD updates)



R&D Project Examples

- Research and Development employs concept development tools and related resources, In-house laboratory area for prototype development, test, evaluation, and data acquisition systems as well as outside resources for specialized processes.
- Examples:
 - System and Subsystem Requirements Definition and Mechanical Design of the Sensor Suite of the Affordable Weapon Technology Demonstrator. (**International Systems**)
 - Cryogenically Cooled Optical Systems for a High Resolution and High Dynamic Response, Real-Time Hyper spectral Imaging Systems for Remote Sensing Applications. (**Navy-Crane**)
 - Developed the Infrared Camera Cold Shutter (IRCCS) for SBFP camera system (Patent Pending). (**Navy-Crane**)
 - Developed a Hand Held In-Situ Bi-directional Reflectometer to measure BRDF of surface properties in the field for BDA and repair. (**Air Force/ Boeing**)
 - Electronic Packaging of CPCI Systems for Ruggedized and Office Environments. (**Military & Multiple Commercial**)
 - Developed Highly Reliable "5-Axis" Magnetic Bearing System for use in Argon-Neon-Fluorine Environment. (**Cymer**)



R&D Project Examples (cont)

- › Tomahawk cruise missile (FCR & Radome)
- › Advanced Cruise Missile (ACM) (Nose Cone and Inertial Guidance system)
- › Ground Based and Hand Held Mine Detection (system design)
- › F-16 Lightweight Electromagnetic Structure (LES)
- › A-12
- › RAH-66 Comanche (displays program- design development)
- › 6522 (Classified)
- › Low A/e coatings (space based Cassegrain antennas)
- › Structured Surfaces
- › FSS
- › Lightweight Computer (ruggedized)
- › MISTI-3 Dual Band Imaging Satellite

Mechanical, Electrical, & Software Engineering Design

- Design requirements review
- Feasibility Study, Concept Development, 0th order analyses
- Electrical, Mechanical, & Software design requirements flow down.
- Preliminary design analysis
- Design review and refinement
- Detail design & analysis
- Prototype fabrication
- Documentation update & Configuration Management
- Pilot production

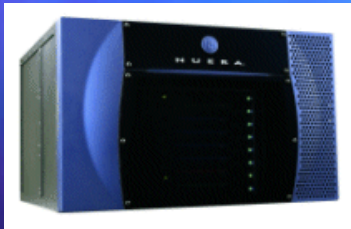
Design Development Examples



- Designed and developed the hand-held directional reflectometer (HHDR). *The device reduces the time to acquire the BRDF from days to minutes.*



- Electronic packaging of compact PCI format electronic modules. *Designed to dissipate 1500 watts of power and meet the NEBS level 4 requirements.*



- The XLA 100 is Cymer's new ultra line-narrowed, high power argon fluoride (arf) production light source for next generation lithography tools. *The optics modules required an ultra pure operating environment to achieve lifetime requirements. 3-D engineering is responsible for the development and design of 1/3 of the modules that make up this state-of-the-art laser system.*



Engineering Analysis & Examples

- Conducted numerous transient and steady state thermal analysis for component and system level performance characterization. *(Examples include: warm-up prediction for the Comanche displays from artic cold, electronic packaging of various formats, cryogenic applications)*
- Conducted structural analysis to determine modal & random vibration characteristics for airborne and ground vehicles. *(Examples include: MISTI-3 dual band imaging satellite, flat panel displays for the **Comanche** helicopter program, a tethered aerostat for remote sensing application, vehicle-based mine detection systems, antenna systems for ship board & ground stations)*
- Analysis for compliance with NEBS requirements for radiated & conducted emissions and fire safety.



File



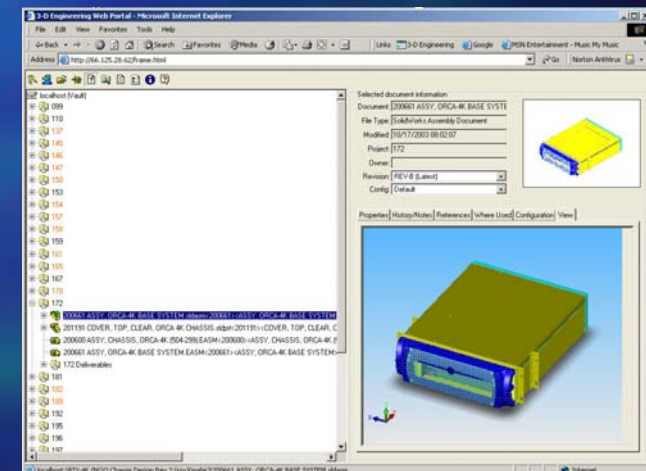
MISTI-3 incorporated several system upgrades to support a more complex remote sensing payload, including one of the first hyperspectral imager instruments ever flown in space. Launched in May 1996 on a Pegasus rocket, the spacecraft collected over 3 million SWIR and MWIR images as well as hyperspectral images. MISTI-3 exceeded its design lifetime by over 50% before being de-orbited in December 1997.



Configuration Management

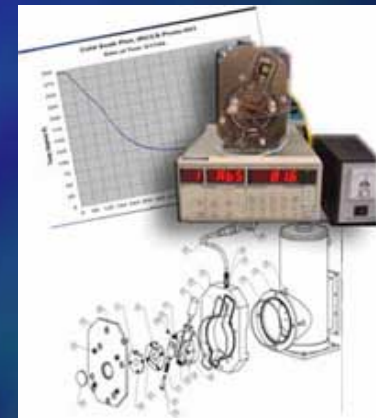
- 3-D employs proven processes and proprietary workflow automation software to streamline the configuration management requirements for a project.
- Our product development process (PDP) requires data item travelers (DIT) for tracking the progress of development during the process.
- All of our data items (models, drawings, specs, OTS, COTS, schematics, board layouts, components libraries) are version controlled in the “as built” or “latest rev” configuration.
- Our “advanced server” system provides secure access to our electronic vault (24/7) via your web browser if the customer so desires.
- Our release manager system performs auto routing of documents (via e-mail) for design approval & review.
- ***Our systems provide the flexibility to conduct development efforts unilaterally as well as a reliable and efficient process to collaborate with our customers regardless of their location or time zone.***

Number	Description	Type	PDF	Doc	Rev	Lifecycle	Status Change
200501	RAIL, RH, ORCA-W CHASSIS	SLDRW			REV.B	UNRELEASED	Is not UNRELEASED
200501	RAIL, RH, ORCA-W CHASSIS	SLDRW			REV.B	UNRELEASED	Is not UNRELEASED
200502	RAIL, LH, ORCA-W CHASSIS	SLDRW			REV.B	UNRELEASED	Is not UNRELEASED
200502	RAIL, LH, ORCA-W CHASSIS	SLDRW			REV.B	UNRELEASED	Is not UNRELEASED
200503	STIFFENER, LWR BACKPLANE, ORCA-W CHASSIS	SLDASM			REV.B	UNRELEASED	Is not UNRELEASED
200503	STIFFENER, LWR BACKPLANE, ORCA-W CHASSIS	SLDRW			REV.B	UNRELEASED	Is not UNRELEASED
200503	STIFFENER, LWR BACKPLANE, ORCA-W CHASSIS	SLDRW			REV.B	UNRELEASED	Is not UNRELEASED
200504	PARTITION, CARD GUIDE, LH, ORCA-W CHASSIS	SLDASM			REV.D.1	PROTOTYPE	Is not PROTOTYPE
200504	PARTITION, CARD GUIDE, LH, ORCA-W CHASSIS	SLDRW			REV.D.1	PROTOTYPE	Is not PROTOTYPE
200504	PARTITION, CARD GUIDE, LH, ORCA-W CHASSIS	SLDRW			REV.D.1	PROTOTYPE	Is not PROTOTYPE
200505	PARTITION, CARD GUIDE, RH, ORCA-W CHASSIS	SLDASM			REV.C.1	PROTOTYPE	Is not PROTOTYPE
200505	PARTITION, CARD GUIDE, RH, ORCA-W CHASSIS	SLDRW			REV.C.1	PROTOTYPE	Is not PROTOTYPE
200505	PARTITION, CARD GUIDE, RH, ORCA-W CHASSIS	SLDRW			REV.C.1	PROTOTYPE	Is not PROTOTYPE
200506	CHASSIS, LOWER, ORCA-W CHASSIS	SLDASM			REV.H.1	LIMITED	Is not LIMITED
200506	CHASSIS, LOWER, ORCA-W CHASSIS	SLDRW			REV.H.1	LIMITED	Is not LIMITED
200507	CHASSIS, UPPER, ORCA-W CHASSIS	SLDASM			REV.B.1	PROTOTYPE	Is not PROTOTYPE
200507	CHASSIS, UPPER, ORCA-W CHASSIS	SLDRW			REV.B.1	PROTOTYPE	Is not PROTOTYPE
200508	BRACKET, FAN TRAY, ORCA-W CHASSIS	SLDASM			REV.B	PROTOTYPE	Is not PROTOTYPE
200508	BRACKET, FAN TRAY, ORCA-W CHASSIS	SLDRW			REV.B	PROTOTYPE	Is not PROTOTYPE
200508	BRACKET, FAN TRAY, ORCA-W CHASSIS	SLDRW			REV.B	PROTOTYPE	Is not PROTOTYPE
200509	PARTITION, REAR, ORCA-W CHASSIS	SLDASM			REV.B.1	UNRELEASED	Is not RELEASED
200509	PARTITION, REAR, ORCA-W CHASSIS	SLDRW			REV.B.1	UNRELEASED	Is not RELEASED
200509	PARTITION, REAR, ORCA-W CHASSIS	SLDRW			REV.B.1	UNRELEASED	Is not RELEASED
200510	GUIDE, CARD, CENTER, ORCA-W CHASSIS	SLDASM			REV.C	UNRELEASED	Is not UNRELEASED
200510	GUIDE, CARD, CENTER, ORCA-W CHASSIS	SLDRW			REV.C	UNRELEASED	Is not UNRELEASED



Test & Evaluation

- Environmental Stress Screening (ESS)
- Airflow testing
- Vibration & Shock
- Temperature
- Humidity
- EMI/RFI
- Resonant Search
- NEBS Testing (Bellcore GR-63)
 - (thermal, earthquake, fire, safety, transportation and storage, operating and non operating, altitude, heat dissipation, Package shock, corrosion)

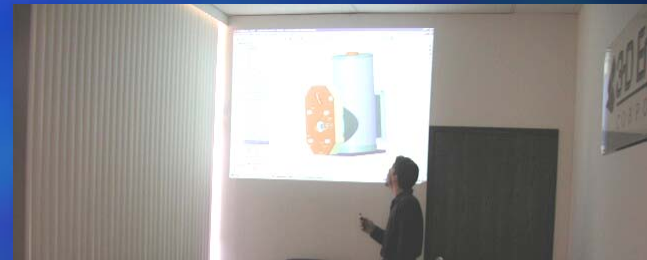


Manufacturing Experience

- Optical systems and devices (Navy-Crane, Cymer, Intralase, AFML)
- Cryogenic design for cooled optical systems (Navy-Crane)
- Laser systems and devices (International Systems, Calhoun, Cymer)
- Sensors and laboratory automation (SAIC)
- Production automation systems (Medical & Commercial)
- Ruggedized electronic chassis and aesthetic panel assemblies (Nuera Calhoun)
- Kinematics and special purpose mechanisms (Intralase)
- Electronic test equipment (Military & Compact PCI customers)

Facilities

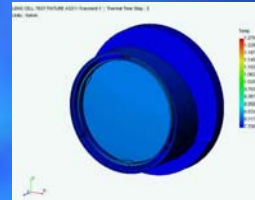
- 8000 sq ft. facility located in Temecula California.
- 1500 sq. ft. devoted to development laboratory and pilot production assembly.
- 3500 sq. ft. devoted to office.
- 3000 sq. ft. Manufacturing
- Inventory Control - receiving through finished goods.



Development Tools

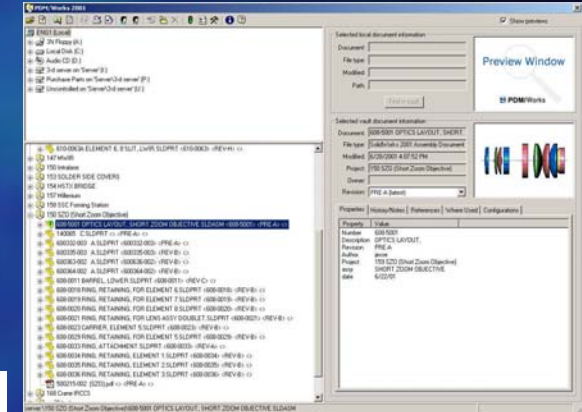
Mechanical Design and Analysis

- SolidWorks (4) + Add-ins
- Wildfire
- CosmosWorks, Stress and Thermal
- Rapid Prototype Capability



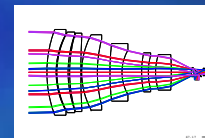
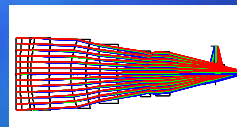
Electrical Design and Analysis

- Orcad Schematic Capture
- Orcad Layout
- ICAP/4 Simulation Software (SPICE)



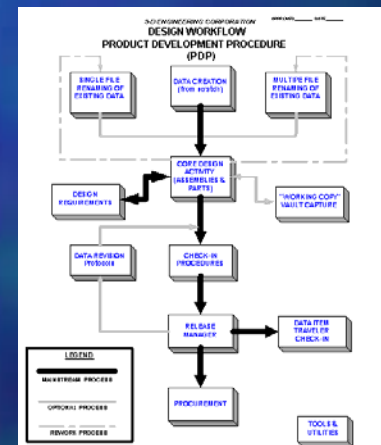
Optical Design and Analysis

- Optis Works
- Code V
- Zemax



Documentation Control and Collaboration

- PDMWorks (Electronic Data Versioning Vault)
- Pro-Intralink
- Advanced Server (Provides Secure Access 24/7)
- Release Manager
- Customized workflow automation with automated notification and documentation



Expertise We Offer

- Affordable Weapon (subsystems, avionics)
- Ruggedized electronics / packaging
- Remote sensing systems (Homeland defense)
- Handheld cryogenic systems
- Test, Evaluation and Integration
- System Engineering
- Compact PCI Requirements

Contact Information

Ms. Linda Luoma

President

(951)296-3060 X204

lluoma@3deng.com

42132 Remington Avenue

Temecula, CA 92590

Tel: (951) 296-3060

Fax: (951) 296-5675